

2MBI225U4N-170-50

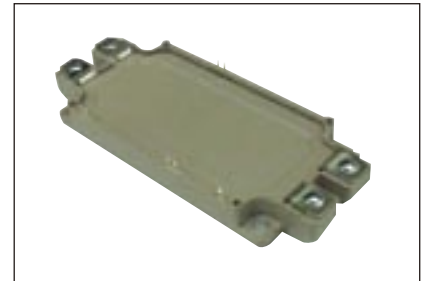
IGBT MODULE (U series) 1700V / 225A / 2 in one package

■ Features

- High speed switching
- Voltage drive
- Low Inductance module structure

■ Applications

- Inverter for Motor Drive
- AC and DC Servo Drive Amplifier
- Uninterruptible Power Supply
- Industrial machines, such as Welding machines



■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings (at Tc=25°C unless otherwise specified)

Items	Symbols	Conditions	Maximum ratings	Units	
Collector-Emitter voltage	V _{CEs}		1700	V	
Gate-Emitter voltage	V _{GES}		±20	V	
Collector current	I _c	Continuous	Tc=25°C	300	A
			Tc=80°C	225	
	I _{cp}	1ms	Tc=25°C	600	
			Tc=80°C	450	
	-I _c		225		
-I _c pulse	1ms	450			
Collector power dissipation	P _c	1 device	1040	W	
Junction temperature	T _j		150	°C	
Storage temperature	T _{stg}		-40 to +125		
Isolation voltage	between terminal and copper base (*1)	AC : 1min.	3400	VAC	
	between thermistor and others (*2)				
Screw torque	Mounting (*3)		3.5	N m	
	Terminals (*4)		4.5		

Note *1: All terminals should be connected together when isolation test will be done.

Note *2: Two thermistor terminals should be connected together, each other terminals should be connected together and shorted to base plate when isolation test will be done.

Note *3: Recommendable value : Mounting : 2.5-3.5 Nm (M5) Note *4: Recommendable value : Terminals : 3.5-4.5 Nm (M6)

● Electrical characteristics (at Tj= 25°C unless otherwise specified)

Items	Symbols	Conditions	Characteristics			Units	
			min.	typ.	max.		
Zero gate voltage collector current	I _{GES}	V _{GE} = 0V, V _{CE} = 1700V	-	-	3.0	mA	
Gate-Emitter leakage current	I _{GES}	V _{CE} = 0V, V _{GE} = ±20V	-	-	600	nA	
Gate-Emitter threshold voltage	V _{GE(th)}	V _{CE} = 20V, I _c = 225mA	4.5	6.5	8.5	V	
Collector-Emitter saturation voltage	V _{CE(sat)} (terminal)	V _{GE} = 15V I _c = 225A	Tj=25°C	-	2.60	2.85	V
			Tj=125°C	-	3.00	-	
	V _{CE(sat)} (chip)		Tj=25°C	-	2.30	2.45	
			Tj=125°C	-	2.65	-	
Input capacitance	C _{ies}	V _{CE} = 10V, V _{GE} = 0V, f = 1MHz	-	21	-	nF	
Turn-on time	t _{on}	V _{CC} = 900V I _c = 225A	-	0.62	1.20	μs	
	t _r		-	0.39	0.60		
	t _{r(i)}		-	0.05	-		
Turn-off time	t _{off}	V _{GE} = ±15V R _G = 2.2Ω	-	0.55	1.50	μs	
	t _f		-	0.09	0.30		
			-	0.09	0.30		
Forward on voltage	V _F (terminal)	V _{GE} = 0V I _F = 225A	Tj=25°C	-	2.05	2.35	V
			Tj=125°C	-	2.25	-	
	V _F (chip)		Tj=25°C	-	1.80	1.95	
			Tj=125°C	-	2.00	-	
Reverse recovery time	t _{rr}	I _F = 225A	-	0.18	0.6	μs	
Lead resistance, terminal-chip (*5)	R lead		-	1.30	-	mΩ	
Thermistor Resistance	R	T=25°C	-	5000	-	Ω	
		T=100°C	465	495	520		
B value	B	T=25/50°C	3305	3375	3450	K	

Note *5: Biggest internal terminal resistance among arm.

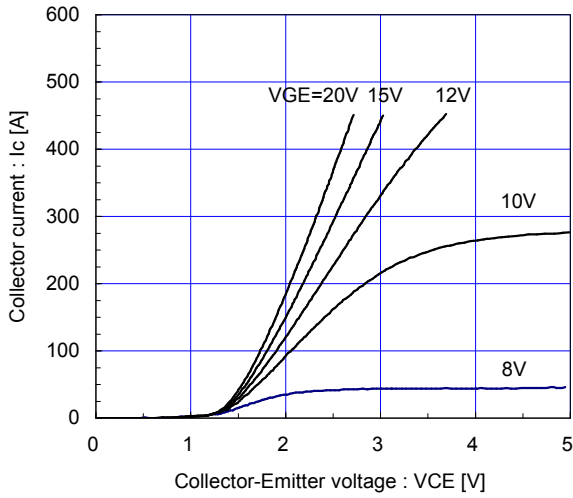
● Thermal resistance characteristics

Items	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Thermal resistance (1device)	R _{th(j-c)}	IGBT FWD	-	-	0.12	°C/W
Contact thermal resistance (1device) (*6)	R _{th(c-f)}	with Thermal Compound	-	0.0167	-	

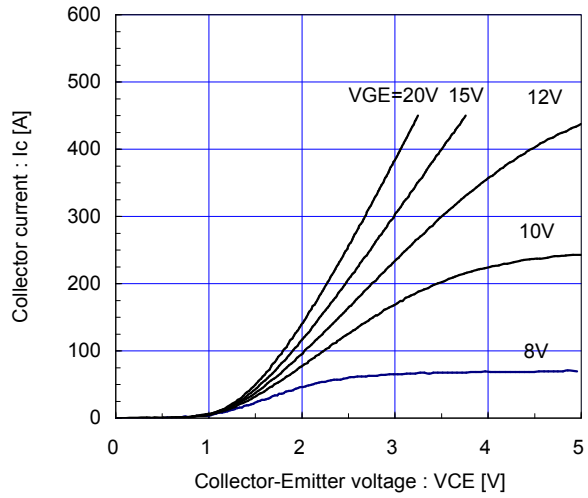
Note *6: This is the value which is defined mounting on the additional cooling fin with thermal compound.

■ Characteristics (Representative)

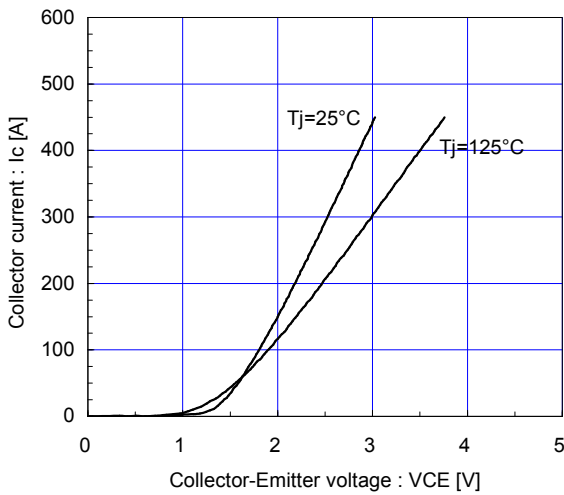
Collector current vs. Collector-Emitter voltage (typ.)
T_j= 25°C / chip



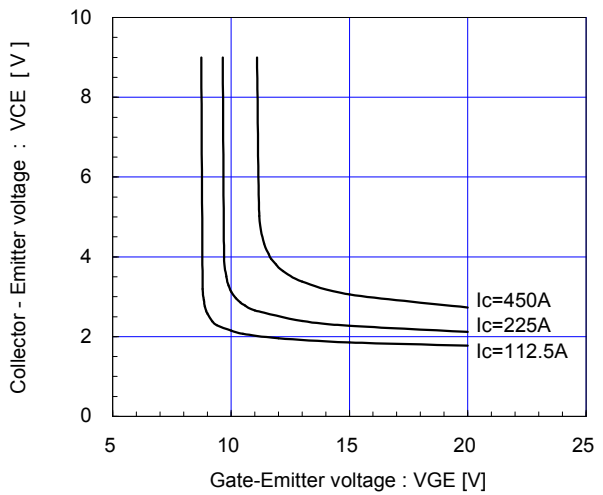
Collector current vs. Collector-Emitter voltage (typ.)
T_j= 125°C / chip



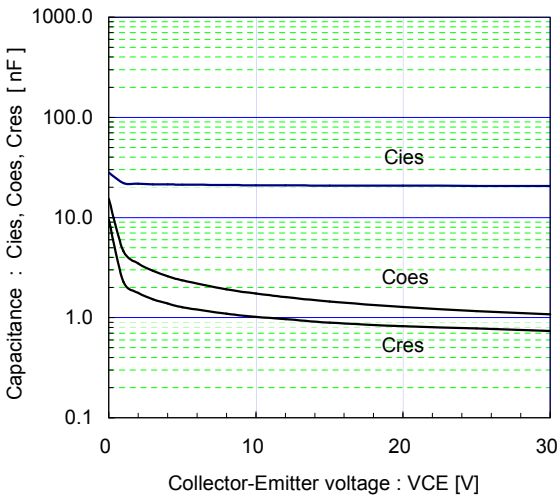
Collector current vs. Collector-Emitter voltage (typ.)
VGE=15V / chip



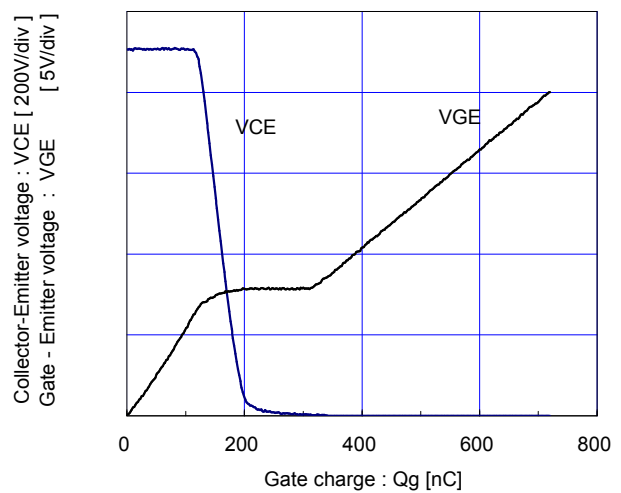
Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)
T_j=25°C / chip

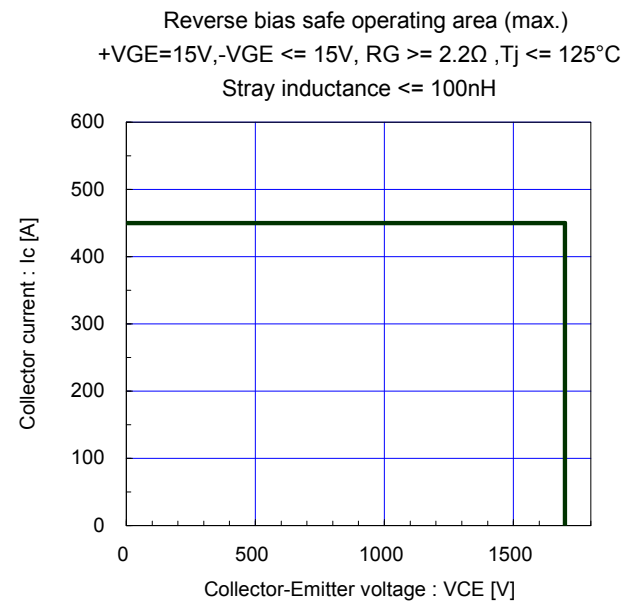
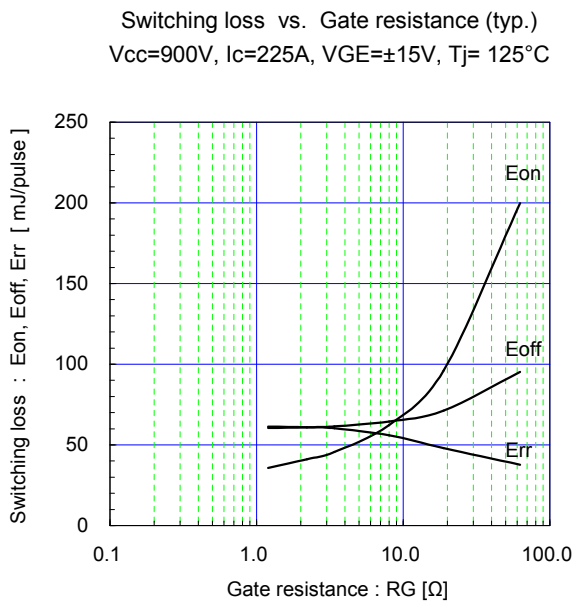
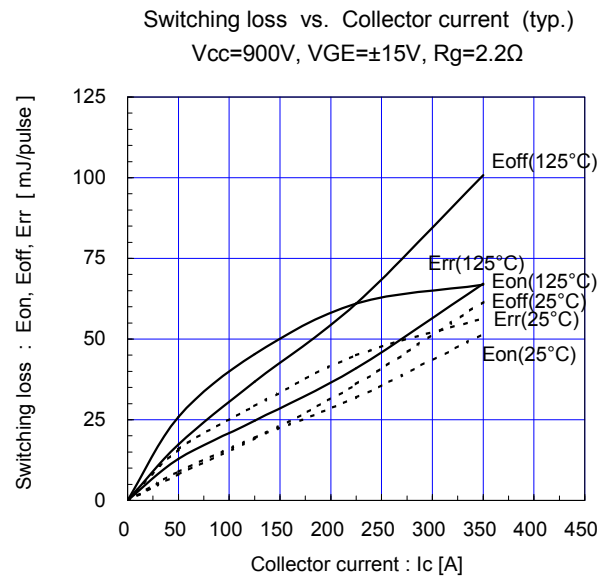
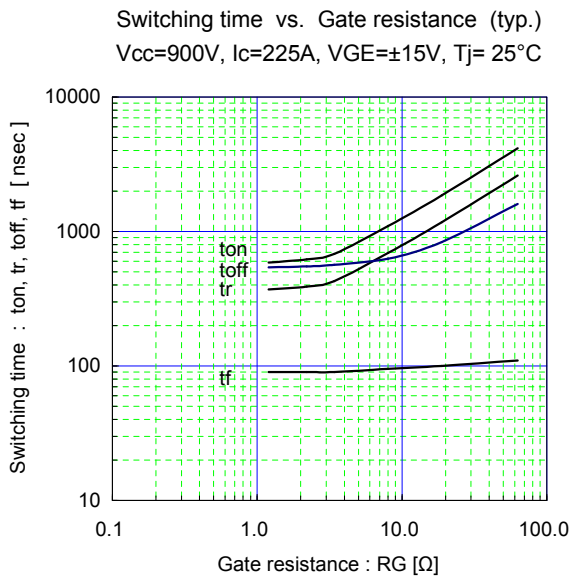
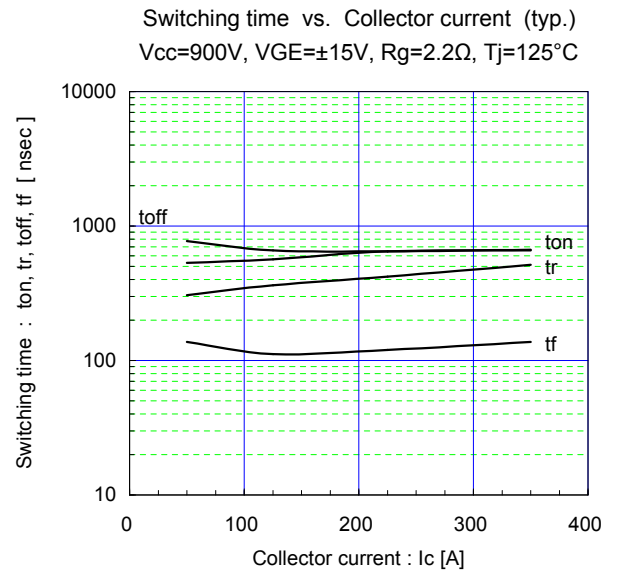
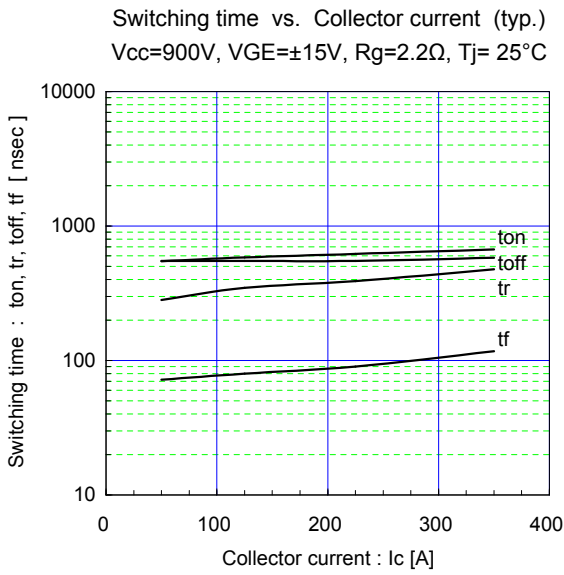


Capacitance vs. Collector-Emitter voltage (typ.)
VGE=0V, f= 1MHz, Tj= 25°C

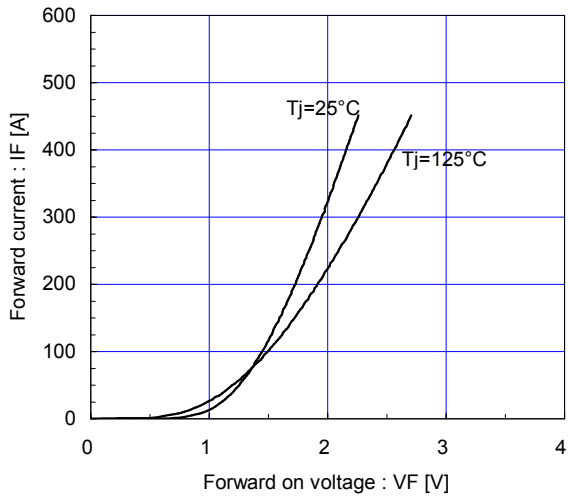


Dynamic Gate charge (typ.)
Vcc=900V, Ic=225A, Tj= 25°C

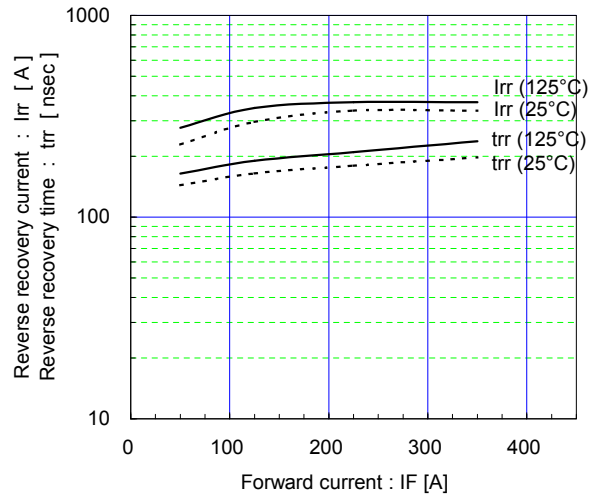




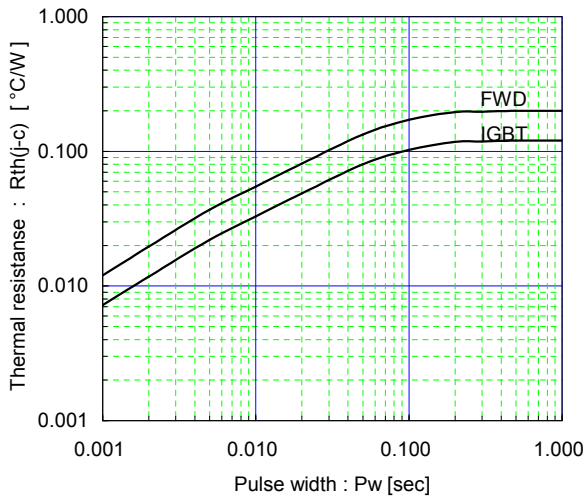
Forward current vs. Forward on voltage (typ.)
chip



Reverse recovery characteristics (typ.)
Vcc=900V, VGE=±15V, Rg=2.2Ω

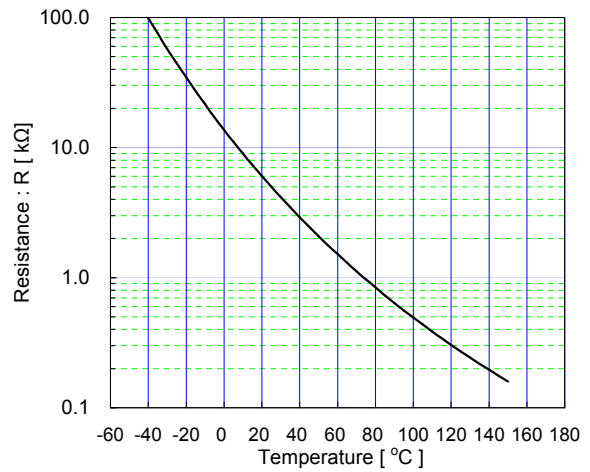


Transient thermal resistance (max.)

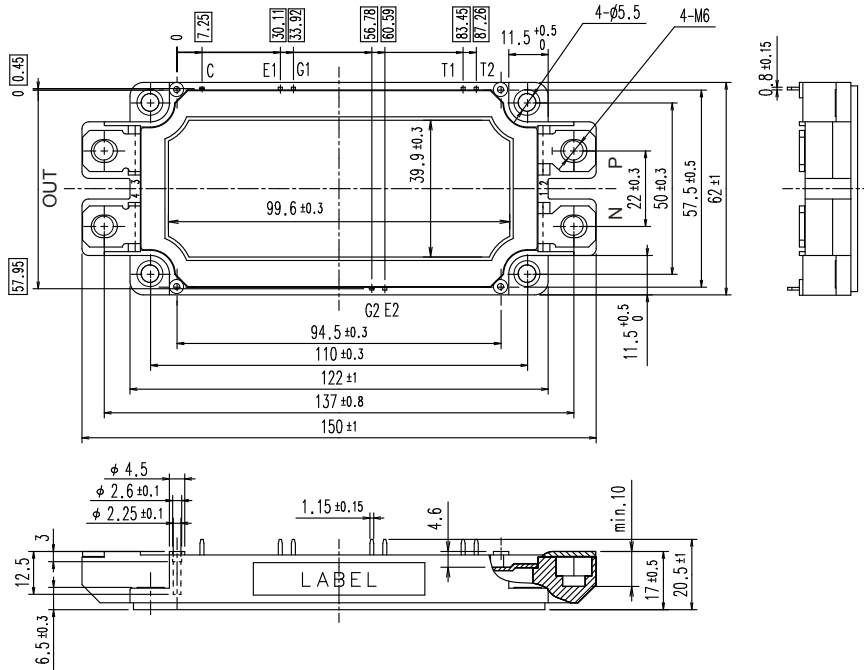


[Thermistor]

Temperature characteristic (typ.)

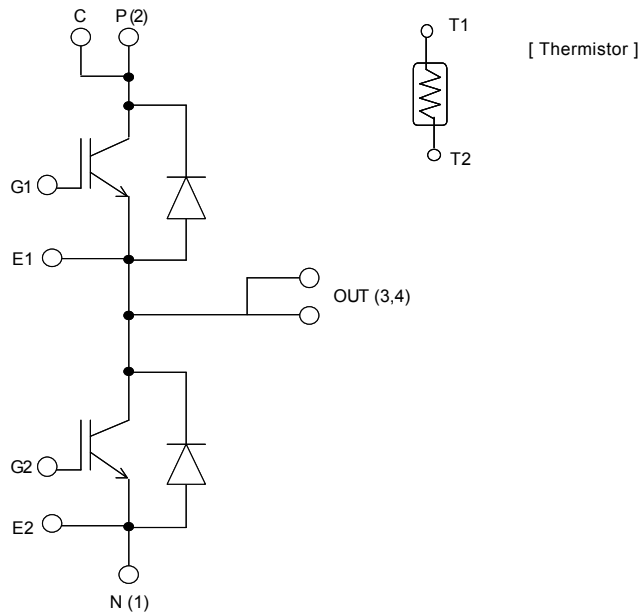


Outline Drawings, mm



NOTE) shows theoretical dimension and tolerance is $\phi \pm 0.5$

Equivalent Circuit Schematic



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